Filename: BOM-PMP10090RevB(001).xls Generate(10/8/2014 5:27:14 PM inverting BuckBoost w/ dual output

Quantity	Designator	Value	Description	PackageReference	PartNumber	Manufacturer
10	C1, C2, C3, C6, C7 C8, C9, C10, C13, C14	22uF	CAP, CERM, 22uF, 25V, +/-10%, X7R, 1210	1210	GRM32ER71E226KE15L	MuRata
3	C4, C5, C11	0.1uF	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603	GRM188R71H104KA93D	MuRata
1	C12	330pF	CAP, CERM, 330 pF, 50 V, +/- 10%, X7R, 0603	0603	GRM188R71H331KA01D	MuRata
1	C101	470pF	CAP, CERM, 470 pF, 100 V, +/- 10%, X7R, 0603	0603	GRM188R72A471KA01D	MuRata
2	D1, D2	40V	Diode, Schottky, 40V, 3A, SMC	SMC	B340-13-F	Diodes Inc.
3	J1, J2, J3		Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm	ED555/2DS	On-Shore Technology
1	L1	33uH	Coupled inductor, 33uH, 2.16A, 0.083 ohm, +/- 20%, SMD	IND_14.8x8.6x14.8mm, SMD	MSD1583-333MEB	Coilcraft
4	NWA black, TP2, TP4, TP6	Black	Test Point, Miniature, Black, TH		5001	Keystone
3	NWA red, TP1, TP3	Red	Test Point, Miniature, Red, TH	Red Miniature Testpoint	5000	Keystone
1	NWA yellow	Orange	Test Point, Miniature, Orange, TH	Orange Miniature Testpoint	5003	Keystone
1	R1	73.2k	RES, 73.2k ohm, 1%, 0.1W, 0603	0603	CRCW060373K2FKEA	Vishay-Dale
1	R2	2.00k	RES, 2.00k ohm, 1%, 0.1W, 0603	0603	CRCW06032K00FKEA	Vishay-Dale
1	R3	49.9	RES, 49.9 ohm, 1%, 0.1W, 0603	0603	CRCW060349R9FKEA	Vishay-Dale
1	R4	10.0k	RES, 10.0 k, 1%, 0.1 W, 0603	0603	CRCW060310K0FKEA	Vishay-Dale
1	R5	412k	RES, 412k ohm, 1%, 0.1W, 0603	0603	CRCW0603412KFKEA	Vishay-Dale
1	R6	280k	RES, 280k ohm, 1%, 0.1W, 0603	0603	CRCW0603280KFKEA	Vishay-Dale
1	R7	49.9k	RES, 49.9k ohm, 1%, 0.1W, 0603	0603	CRCW060349K9FKEA	Vishay-Dale
1	R101	100	RES, 100, 5%, 0.25 W, 1206	1206	CRCW1206100RJNEA	Vishay-Dale
1		Blue	Test Point, Miniature, Blue, TH		5117	Keystone
1	TP7	White	Test Point, Miniature, White, TH	White Miniature Testpoint	5002	Keystone
1	U1		60 V Input, 3.5 A, Step Down DC-DC Converter with Eco-mode, DDA0008E	DDA0008E	TPS54360DDA	Texas Instruments

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